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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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HZM6.8MWA

Silicon Planar Zener Diode for Surge Absorb



ADE-208-851A (Z)

Rev.1
Nov. 2001

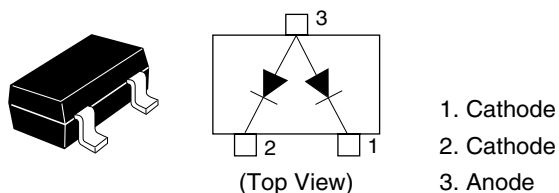
Features

- HZM6.8MWA has two devices in a monolithic, and can absorb surge.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HZM6.8MWA	68M	MPAK

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: Two device total, See Fig.2.

Electrical Characteristics*¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _z	6.47	—	7.00	V	I _z = 5 mA, 40 ms pulse
Reverse current	I _R	—	—	2	μA	V _R = 3.5 V
Capacitance	C	—	—	130	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	—	—	30	Ω	I _z = 5 mA
ESD-Capability * ² , * ³	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes: 1. Per one device.

2. Failure criterion ; I_R > 2 μA at V_R = 3.5 V.

3. Between cathode and anode

Main Characteristic

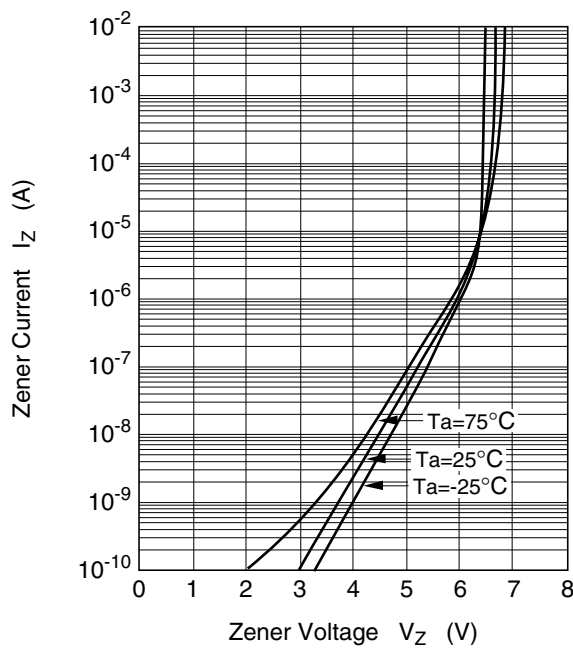


Fig.1 Zener current vs. Zener voltage

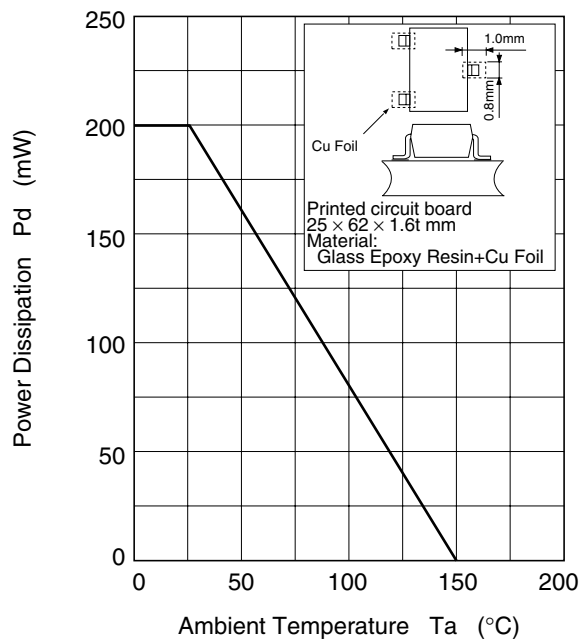
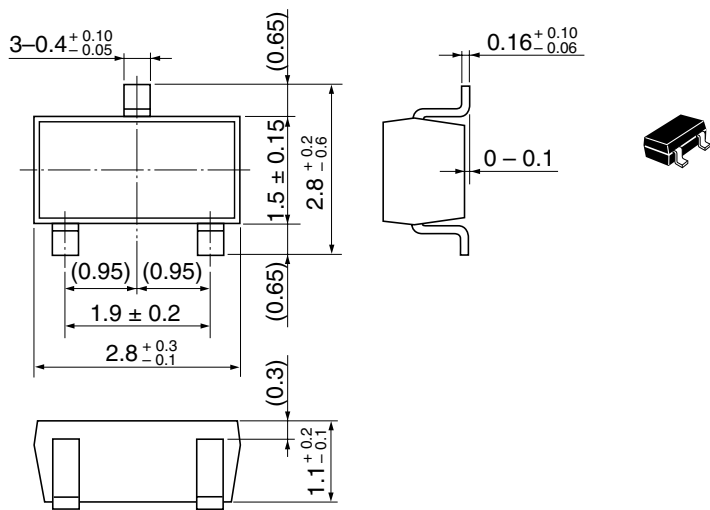


Fig.2 Power Dissipation vs. Ambient Temperature

Package Dimensions

As of July, 2001
Unit: mm



Hitachi Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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